

R2A20112SP/DD

R19DS0079EJ0400

Rev.4.00

Critical Conduction Mode Interleaved PFC Control IC

Dec 13, 2014

Description

The R2A20112 controls a boost converter to provide an active power factor correction.

The R2A20112 adopts critical conduction mode for power factor correction and realizes high efficiency and a low switching noise by zero current switching.

Interleaving function improve ripple current on input or output capacitor by 180 degrees phase shift.

The feedback loop open detection, two mode overvoltage protection, overcurrent protection are built in the R2A20112, and can constitute a power supply system of high reliability with few external parts.

Features

- Maximum Ratings
 - Supply voltage Vcc: 24 V
 - Operating junction temperature Tjopr: -40 to +150°C
- Electrical characteristics
 - VREF output voltage VREF: 5.0 V ± 3%
 - UVLO operation start voltage VH: 10.5 V ± 0.7 V
 - UVLO operation shutdown voltage VL: 9.3 V ± 0.5 V
 - UVLO hysteresis voltage HysuVL: 1.2 V ± 0.5 V
- Functions
 - Boost converter control with critical conduction mode
 - Interleaving control
 - Two mode overvoltage protection
 - Mode1: Dynamic OVP corresponding to a voltage rise by load change
 - Mode2: Static OVP corresponding to overvoltage in stable
 - Feedback loop open detection
 - Master and Slave independence overcurrent protection
 - 280 μs restart timer
 - Package lineup: Pb-free SOP-16/DILP-16*

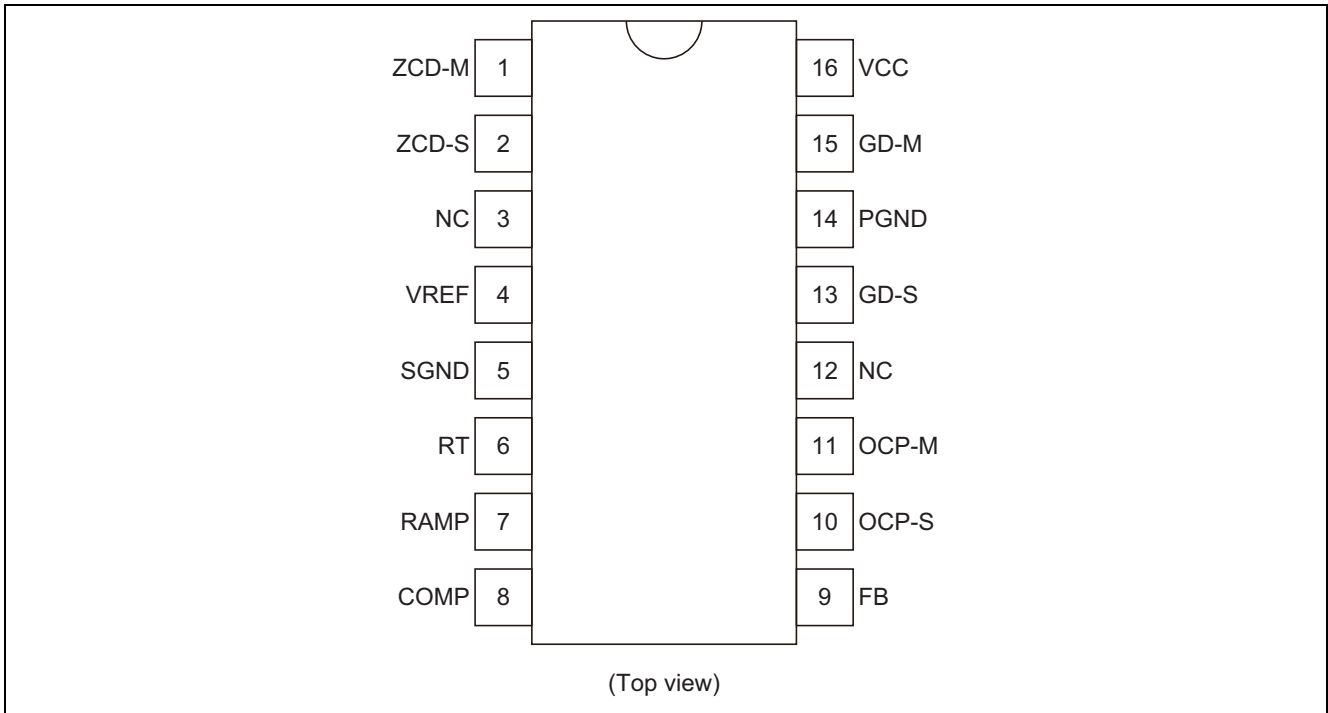
Note: * Not recommend for new design.

Ordering Information

Part No.	Package Name	Package Code	Taping Spec.
R2A20112SPW0	FP-16DAV	PRSP0016DH-B	2000 pcs./one taping product
R2A20112DDU0 *	DP-16FV	PRDP0016AE-B	—

Note: * Not recommend for new design.

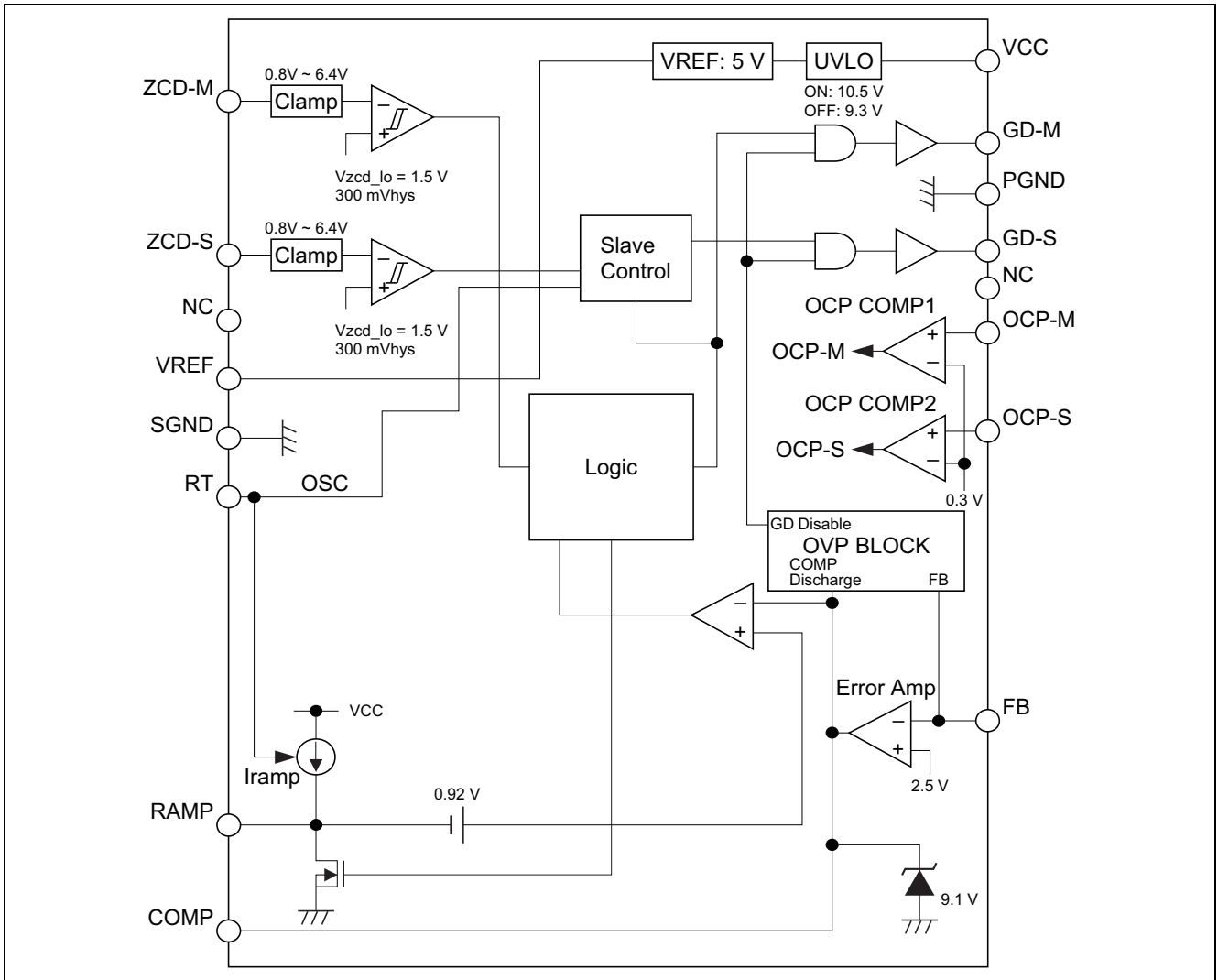
Pin Arrangement



Pin Functions

Pin No.	Pin Name	Input/Output	Function
1	ZCD-M	Input	Master converter zero current detection input terminal
2	ZCD-S	Input	Slave converter zero current detection input terminal
3	N.C.	—	Open
4	VREF	Output	Reference voltage output terminal
5	SGND	—	Ground for small signal circuit
6	RT	Input/Output	Oscillator frequency setting terminal
7	RAMP	Input/Output	Ramp waveform setting terminal
8	COMP	Output	Error amplifier output terminal
9	FB	Input	Error amplifier input terminal
10	OCP-S	Input	Slave converter overcurrent detection terminal
11	OCP-M	Input	Master converter overcurrent detection terminal
12	N.C.	—	Open
13	GD-S	Output	Slave converter Power MOSFET drive terminal
14	PGND	—	Ground for power stage
15	GD-M	Output	Master converter Power MOSFET drive terminal
16	VCC	Input	Supply voltage terminal

Block Diagram



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit	Note
Supply voltage	Vcc	-0.3 to 24	V	
GD-M Peak current	Ipk-gdm	±200	mA	3
GD-M DC current	I _{dc} -gdm	±10	mA	
GD-S Peak current	Ipk-gds	±200	mA	3
GD-S DC current	I _{dc} -gds	±10	mA	
ZCD terminal current	I _{zcd}	±10	mA	
RT terminal current	I _{rt}	-200	μA	
Vref terminal current	I _{ref}	-5	mA	
COMP terminal current	I _{comp}	±1	mA	
Terminal voltage	V _t -group1	-0.3 to Vcc	V	4
	V _t -group2	-0.3 to Vref	V	5
Vref terminal voltage	V _t -ref	-0.3 to Vref+0.3	V	
Power dissipation	P _t	1	W	6
Operating junction temperature	T _j -opr	-40 to +150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

- Notes:
- Rated voltages are with reference to the SGND terminal.
 - For rated currents, inflow to the IC is indicated by (+), and outflow by (-).
 - Shows the transient current when driving a capacitive load.
 - This is the rated voltage for the following pins:
RAMP, FB
 - This is the rated voltage for the following pins:
RT, OCP-M, OCP-S
 - In case of R2A20112DD (DILP): $\theta_{ja} = 120^{\circ}\text{C}/\text{W}$ (Not recommend for new design)
In case of R2A20112SP (SOP): $\theta_{ja} = 120^{\circ}\text{C}/\text{W}$
This value is a thing mounting on $40 \times 40 \times 1.6$ [mm], a glass epoxy board of wiring density 10%.

Electrical Characteristics

(Ta = 25°C, Vcc = 12 V, RT = 22 kΩ, OCP = GND, CRAMP = 680 pF, RZCD-GND = 51 kΩ, FB = COMP)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	
Supply	UVLO Turn-on threshold	V _{uvlh}	9.8	10.5	11.2	V	
	UVLO Turn-off threshold	V _{uvll}	8.8	9.3	9.8	V	
	UVLO hysteresis	H _{ysv_l}	0.7	1.2	1.7	V	
	Standby current	I _{stby}	—	120	200	μA	Vcc = 8.9 V, ZCD = Open
	Operating current	I _{cc}	—	4.9	7.0	mA	
VREF	Output voltage	V _{ref}	4.85	5.00	5.15	V	I _{source} = -1 mA
	Line regulation	V _{ref} -line	—	5	20	mV	I _{source} = -1 mA, Vcc = 10 V to 24 V
	Load regulation	V _{ref} -load	—	5	20	mV	I _{source} = -1 mA to -5 mA
	Temperature stability	dV _{ref}	—	±80	—	ppm/°C	Ta = -40 to 125°C *1

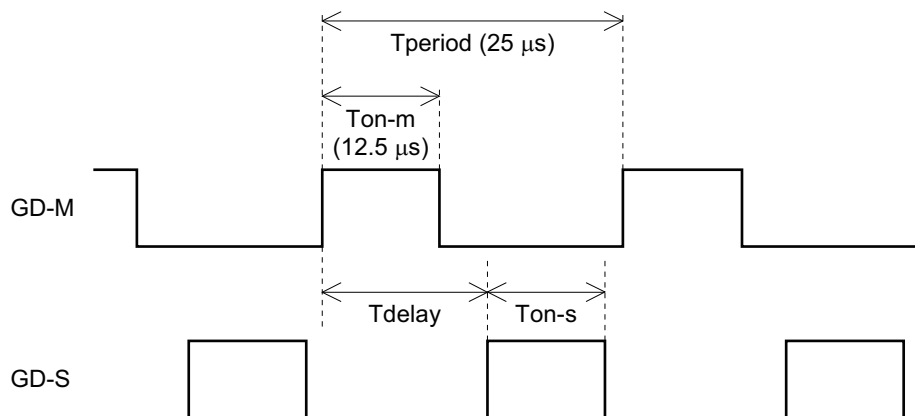
- Note: 1. Design spec.

Electrical Characteristics (cont.)

($T_a = 25^\circ\text{C}$, $V_{cc} = 12\text{ V}$, $R_T = 22\text{ k}\Omega$, $OCP = \text{GND}$, $CRAMP = 680\text{ pF}$, $RZCD\text{-GND} = 51\text{ k}\Omega$, $FB = \text{COMP}$)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	
Error amplifier	Feedback voltage	Vfb	2.40	2.50	2.60	V	FB-COMP short, RAMP = 0 V
	Input bias current	I _{fb}	-0.5	0	0.5	μA	Measured pin: FB
	Open loop gain	A _v	—	60	—	dB	*1
	Upper clamp voltage	V _{clamp-comp}	8.0	9.1	10.6	V	FB = 2.0 V, COMP: Open
	Low voltage	V _{l-comp}	—	0.1	0.3	V	FB = 3.0 V, COMP: Open
	Source current	I _{src-comp}	—	-120	—	μA	FB = 1.5 V, COMP = 2.5 V
	Sink current 1	I _{snkcomp1}	—	120	—	μA	*1
	Sink current 2	I _{snkcomp2}	—	300	—	μA	FB = 3.5 V, COMP = 2.5 V
Transconductance	g _m	150	200	290	μs	FB = 2.45 V ↔ 2.55 V, COMP = 2.5 V	
RAMP	RAMP charge current	I _{c-ramp}	130	150	170	μA	RAMP = 0 V to 7 V
	RAMP discharge current	I _{d-ramp}	7	16	29	mA	FB = 1 V, COMP = 2 V, RAMP = 0 V to 1.5 V to 1 V
	Low voltage	V _{l-ramp}	—	17	200	mV	FB = 1 V, COMP = 3 V, RAMP = 0 V to 2.5 V to open I _{sink} = 100 μA
Zero current detector	Upper clamp voltage	V _{zcdh}	5.8	6.4	7.0	V	I _{source} = -3 mA
	Lower clamp voltage	V _{zcdl}	0.3	0.8	1.3	V	I _{sink} = 3 mA
	ZCD low threshold voltage	V _{zcd_lo}	1.05	1.50	1.75	V	*1
	ZCD hysteresis	H _{yszcd}	180	300	390	mV	*1
	Input bias current	I _{zcd}	-1	—	1	μA	1.2 V < V _{zcd} < 5 V
Slave control	Phase delay	Phase	160	180	200	deg.	*1, *2
	On time ratio	T _{on-ratio}	-5	—	5	%	*1, *2
Restart	Restart time delay	T _{start}	210	280	350	μs	Cramp = 3300 pF FB = 2.0 V, COMP = 5 V

Notes: 1. Design spec.
2.



$$\text{Phase} = \frac{T_{\text{delay}}}{T_{\text{period}}} \times 360 \text{ [deg.]}$$

$$\text{Ton-ratio} = \left(1 - \frac{T_{\text{on-s}}}{T_{\text{on-m}}}\right) \times 100 \text{ [%]}$$

Electrical Characteristics (cont.)

(Ta = 25°C, Vcc = 12 V, RT = 22 kΩ, OCP = GND, CRAMP = 680 pF, RZCD-GND = 51 kΩ, FB = COMP)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	
Gate drive	Master gate drive rise time	tr-gdm	—	30	100	ns	CL = 100 pF, Cramp = 3300 pF FB = 2.0 V, COMP = 5 V
	Slave gate drive rise time	tr-gds	—	30	100	ns	CL = 100 pF, Cramp = 3300 pF FB = 2.0 V, COMP = 5 V
	Master gate drive fall time	tf-gdm	—	30	100	ns	CL = 100 pF, Cramp = 3300 pF FB = 2.0 V, COMP = 5 V
	Slave gate drive fall time	tf-gds	—	30	100	ns	CL = 100 pF, Cramp = 3300 pF FB = 2.0 V, COMP = 5 V
	Master gate drive low voltage	Vol1-gdm	—	0.05	0.2	V	Isink = 2 mA
		Vol2-gdm	—	0.03	0.7		Isink = 1 mA, VCC = 5 V
	Master gate drive high voltage	Voh-gdm	11.5	11.9	—	V	Isource = -2 mA
	Slave gate drive low voltage	Vol1-gds	—	0.05	0.2	V	Isink = 2 mA
Vol2-gds		—	0.03	0.7	Isink = 1 mA, VCC = 5 V		
Slave gate drive high voltage	Voh-gds	11.5	11.9	—	V	Isource = -2 mA *1	
Over current protection	OCP threshold voltage	Vocp	0.27	0.3	0.33	V	
Over voltage protection	Dynamic OVP threshold voltage	Vdovp	VFB× 1.035	VFB× 1.050	VFB× 1.065	V	
	Static OVP threshold voltage	Vsovp	VFB× 1.075	VFB× 1.090	VFB× 1.105	V	COMP = Open
	Static OVP hysteresis	Hys-sovp	50	100	150	mV	COMP = Open
	FB open detect threshold voltage	Vfbopen	0.45	0.50	0.55	V	COMP = Open
	FB open detect hysteresis	Hysfbopen	0.16	0.20	0.24	V	COMP = Open

Note: 1. Design spec.

Package Dimensions

JEITA Package Code P-SOP16-5.5x10.06-1.27	RENEASAS Code PRSP0016DH-B	Previous Code FP-16DAV	MASS[Typ.] 0.24g
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NOTE)
1. DIMENSIONS**1 (Nom)*AND**2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3*DOES NOT
INCLUDE TRIM OFFSET.

Terminal cross section
(Ni/Pd/Au plating)

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _P	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
HE	7.50	7.80	8.00
⌀	—	1.27	—
x	—	—	0.12
y	—	—	0.15
z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

JEITA Package Code P-DIP16-6.3x19.2-2.54	RENEASAS Code PRDP0016AE-B	Previous Code DP-16FV	MASS[Typ.] 1.05g
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(Ni/Pd/Au plating)

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e ₁	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A ₁	0.51	—	—
b _P	0.40	0.48	0.56
b ₃	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.12
L	2.54	—	—

not recommend for new design

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